**DATE 28 JUN 2010** 



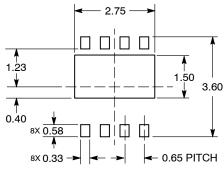
**DETAIL Z** 

U 4X

## **DFN8 3x3, (MICRO8 LEADLESS)** CASE 846C-01 ISSUE D T SEATING PLANE SCALE 4:1 ΔΔ INDEX AREA вГ R NOTF 6 6 F 5 0.15 2X AA **TOP VIEW** 0.15 Т 0.10 T 8X □ 0.08 T NOTE 4 0.10 TWY Ф W SIDE VIEW 0.05 Τ| L 8X D<sub>8</sub>x 8 1 L1 NOTE 4 **G** 6X 6 3 5 4

## **SOLDERING FOOTPRINT\***

VIEW AA-AA



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES:
  1. DIMENSIONS AND TOLERANCING PER ASME
- Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETER.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- DIMENSION D APPLIES TO METALLIZED
  TERMINAL AND IS MEASURED BETWEEN 0.25 MM AND 0.30 MM FROM TERMINAL TIP.
  DIMENSION L1 IS THE TERMINAL PULL BACK FROM PACKAGE EDGE, UP TO 0.1 MM IS ACCEPTABLE. L1 IS OPTIONAL.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- OPTIONAL SIDE VIEW CAN SHOW LEADS 5 AND 8 REMOVED.

	MILLIMETERS		
DIM	MIN	MAX	
Α	3.30 BSC		
В	3.30 BSC		
С	0.85	0.95	
D	0.25	0.35	
E	1.30	1.50	
F	2.55	2.75	
G	0.65 BSC		
Н	0.95	1.15	
J	0.25 BSC		
K	0.00	0.05	
L	0.35	0.45	
L1	0.00	0.10	
P	1.28	1.38	
U	0.17 TYP		

## **GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code = Assembly Location Α

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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**DETAIL Z** 

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